



*Reliance Computer Corp.*

***PC133 SDRAM  
Forum***

***March 9, 1999***

# Agenda



- 1:10-1:30 PC133 Program Update (David Pulling, RCC)
- 1:30-2:00 PC133 Market Demand (Bert McComas, InQuest)
- 2:00-3:00 PC133 0.9 Specs & DIMMs Tech. (Mark Kellogg, IBM)
- 3:00-3:20 Short Break & Hardware Demos
- 3:30-4:00 PC133 Clock Reference Board (Cecil Ho, CST)
- 4:00-4:30 PC133 Superior Margin to PC100 (Mike Siebert, Micron)
- 4:30-5:00 Detailed Signal Analysis (Jeon Taek Im, Samsung)
- 5:00-5:30 Via Chipset & PC133 (Eric Chang, Via)
- 5:30-6:00 Future Direction (David Pulling, RCC)

# Top 11 Reasons to Use PC133



11. Natural Evolution of PC100
10. JEDEC Compliant
9. Chip Kill Support
8. Lower Latency
7. No New Fabs or Testers
6. Balanced Bandwidth
5. More Memory for your \$\$
4. Large Memory Support
3. No Royalties \$\$
2. Memory Vendors can Actually Build it!
1. It Works !

# PC133 Industry Momentum



## OEMs

- Compaq
- DELL
- Hitachi
- HP
- IBM
- Intergraph
- NEC
- Sun
- Fujitsu
- Others

## Suppliers

- Fujitsu
- Hitachi
- Hyundai
- IBM
- LG
- Micron
- Mitsubishi
- NEC
- Samsung
- Siemens
- Toshiba

## Controllers

- RCC
- Via
- SIS
- Acer
- AMD
- Sun
- Other Unix
- Graphics
- Networking

# Successful PC133 Testing

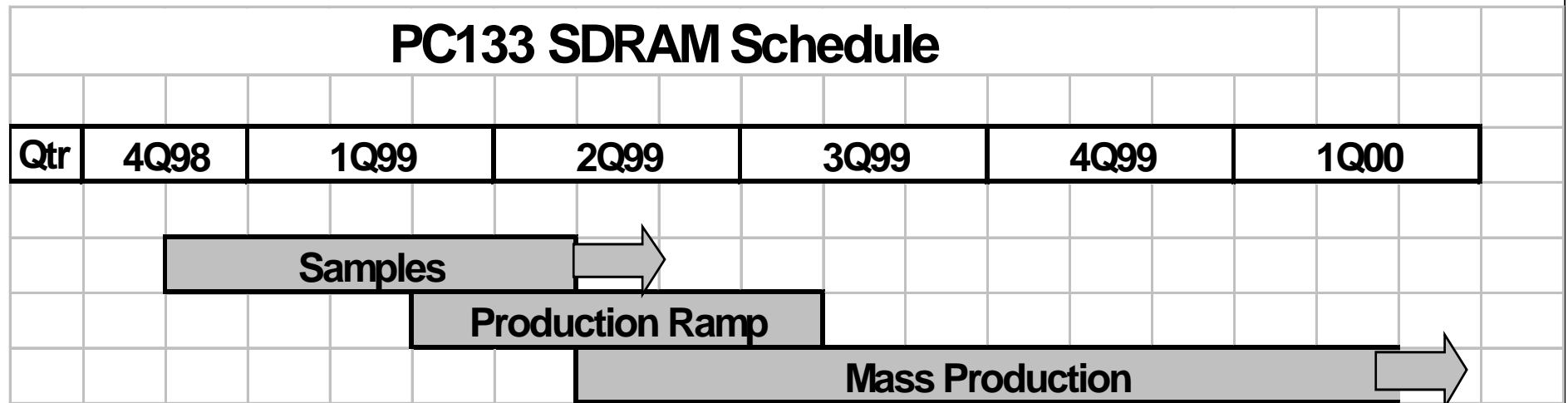


- Successfully testing 9 Suppliers PC133 DIMMs
  - Remaining 2 suppliers to ship parts next week
- Successfully testing Raw Cards “A” and “B”
  - Card A: 64 MB
  - Card B: 128 MB
  - Card B: 256 MB (stacked 64Mbit & non-stacked 128Mbit)
  - Card B: 512 MB (stacked 128Mbit & non-stacked 256Mbit)
- Reliance Supplier Hosting Program
  - Suppliers come to RCC’s labs for 2-3 days intensive analysis and testing
  - Already hosted 4 suppliers
  - Please coordinate w/ RCC to arrange times

# PC133 Production



## PC133 SDRAM Schedule



- Top 11 Suppliers currently sampling PC133 DIMMs
- Systems will Ship “133 MHz Ready” 2Q99
- Full Production Ramp starts 2Q99

# Future Direction

# Future Direction



- **DDR** the optimum Technology to meet future Server and Workstation requirements
  1. High Bandwidth Capability (4 - 8 GB/s)
  2. Low Latency Architecture
  3. Enterprise Chip Kill Support
  4. Superior Cost Structure
  5. Large Memory Support (8 - 64 GB's)